



DC Input 8-Pin Phototransistor Optocoupler

Features

- High isolation 5000 VRMS
- DC input with transistor output
- Operating temperature range - 55 °C to 110 °C
- External Creepage $\geq 7.5\text{mm}$ (S/SL Type)
- External Creepage $\geq 8.0\text{mm}$ (SLM Type)
- RoHS compliant
- REACH compliance
- Green material
- Regulatory Approvals
 - UL - UL1577 (E364000)
 - VDE - EN60747-5-5(VDE0884-5)
 - CQC – GB4943.1, GB8898
 - IEC60065, IEC60950

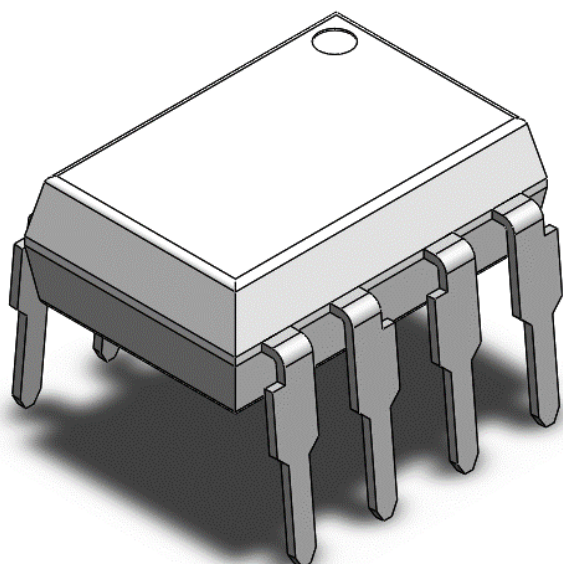
Description

The CT827 series consists of dual channels each contains a photo transistor optically coupled to a gallium arsenide Infrared-emitting diode in a 8-lead DIP package different lead forming options.

Applications

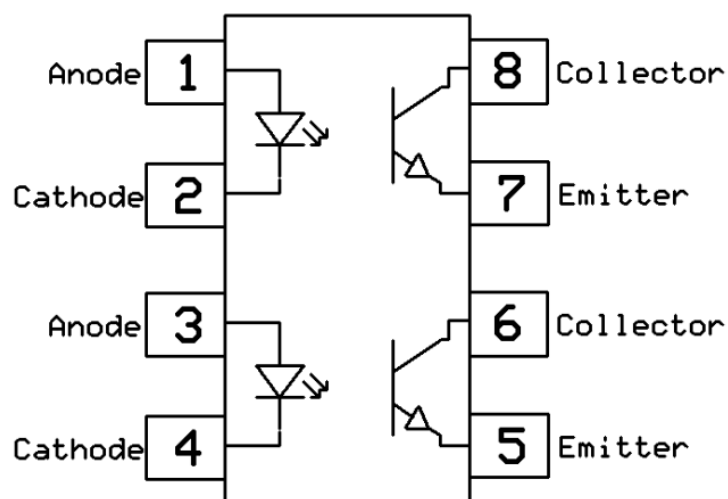
- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Package Outline



Note: Different lead forming options available. See package dimension.

Schematic



**Absolute Maximum Rating at 25°C**

Symbol	Parameters	Ratings	Units	Notes
V _{ISO}	Isolation voltage	5000	V _{RMS}	
P _{TOT}	Total power dissipation	200	mW	
T _{OPR}	Operating temperature	-55 ~ +110	°C	
T _{STG}	Storage temperature	-55 ~ +150	°C	
T _{SOL}	Soldering temperature	260	°C	
Emitter (1 circuit)				
I _F	Forward current	60	mA	
I _{F(TRANS)}	Peak transient current (≤1μs P.W,300pps)	1	A	
V _R	Reverse voltage	6	V	
P _D	Emitter power dissipation	100	mW	
Detector (1 circuit)				
P _D	Detector power dissipation	150	mW	
B _{VCEO}	Collector-Emitter Breakdown Voltage	80	V	
B _{VECO}	Emitter-Collector Breakdown Voltage	7	V	
I _C	Collector Current	50	mA	

**Electrical Characteristics** $T_A = 25^\circ\text{C}$ (unless otherwise specified)**Emitter Characteristics**

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V_F	Forward voltage	$I_F = 10\text{mA}$		1.24	1.4	V	
I_R	Reverse Current	$V_R = 6\text{V}$	-	-	5	μA	
C_{IN}	Input Capacitance	$f = 1\text{MHz}$	-	10	30	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$B_{V_{CEO}}$	Collector-Emitter Breakdown	$I_C = 100\mu\text{A}$	80	-	-	V	
$B_{V_{ECO}}$	Emitter-Collector Breakdown	$I_E = 100\mu\text{A}$	7	-	-	V	
I_{CEO}	Collector-Emitter Dark Current	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$	-	-	100	nA	

Transfer Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes			
CTR	Current Transfer Ratio	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$				%				
								CT827	50	600
								CT827A	80	160
	CT827B	130	260							
$V_{CE(SAT)}$	Collector-Emitter Saturation Voltage	$I_F = 20\text{mA}, I_C = 1\text{mA}$	-	0.1	0.2	V				
R_{IO}	Isolation Resistance	$V_{IO} = 500\text{V}_{DC}$	5×10^{10}			Ω				
C_{IO}	Isolation Capacitance	$f = 1\text{MHz}$		0.5	1	pF				

Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
t_r	Rise Time	$I_C = 2\text{mA}, V_{CE} = 2\text{V}$	-	6	18	μs	
t_f	Fall Time	$R_L = 100\Omega$	-	8	18		



Typical Characteristic Curves

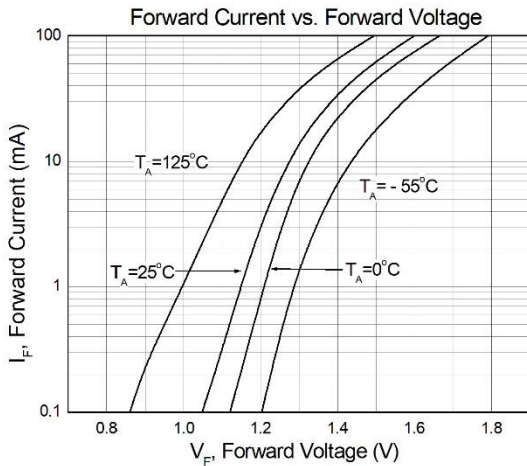


Figure 2

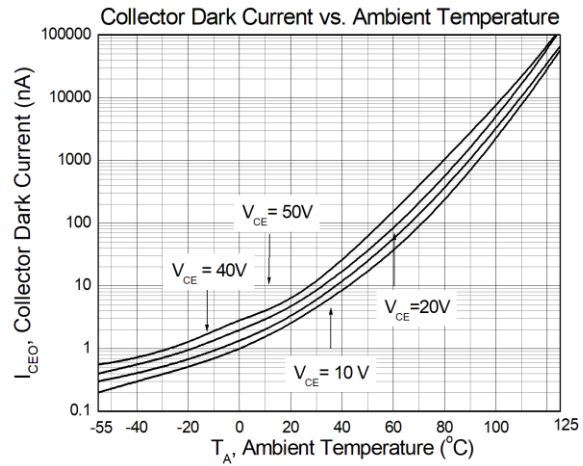


Figure 3

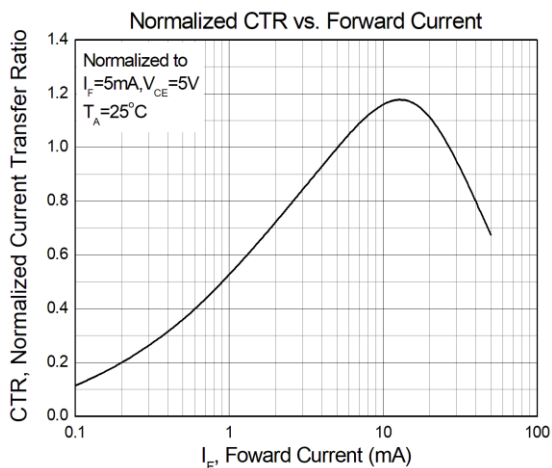


Figure 4

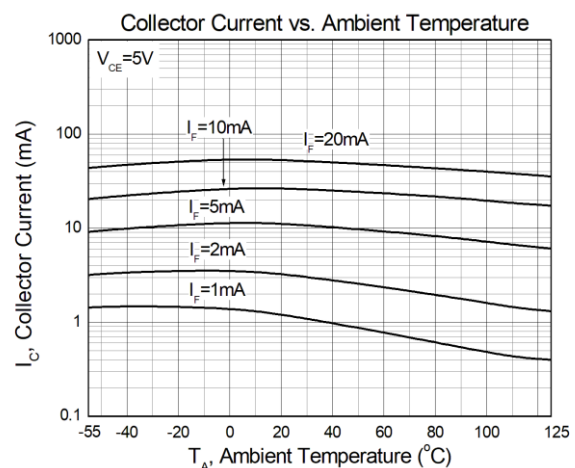


Figure 5

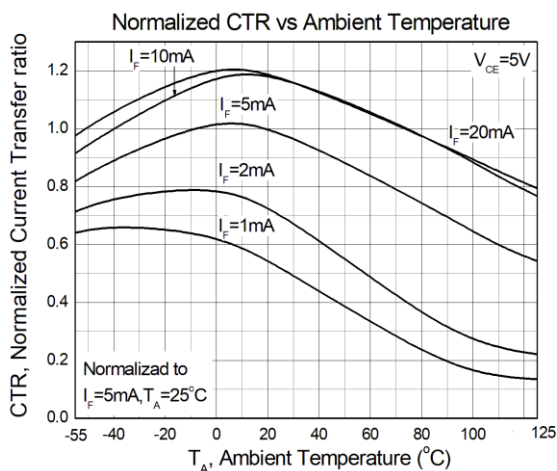


Figure 6

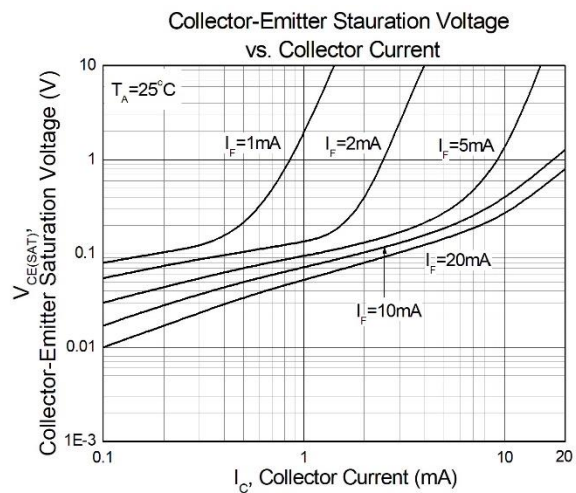


Figure 7



Collector-Emitter Saturation Voltage vs. Forward Current

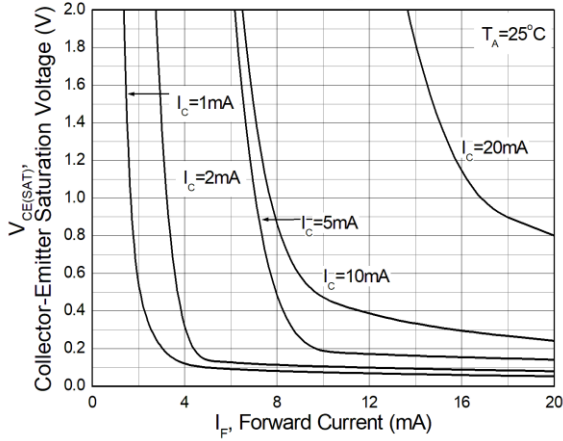


Figure 8

Switching Speed vs. Load Resistance

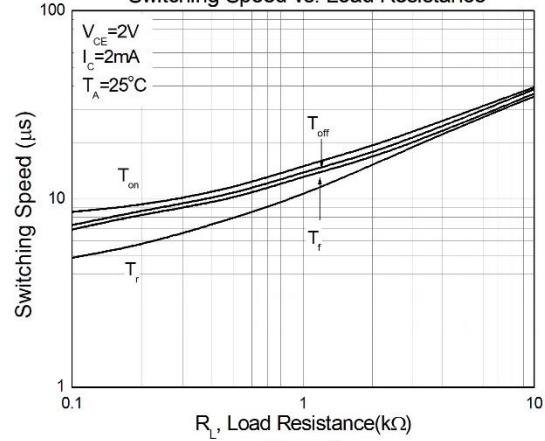


Figure 9

Voltage Gain vs. Frequency

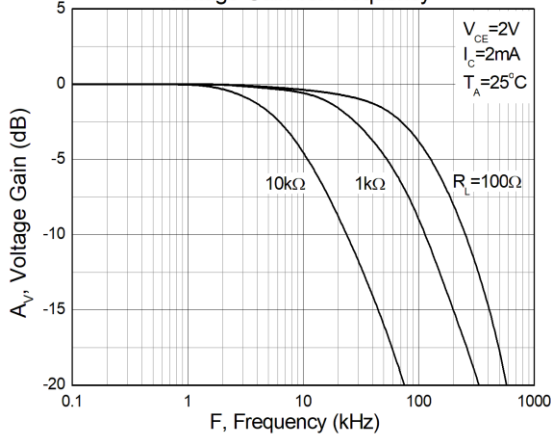


Figure 10



Test Circuit

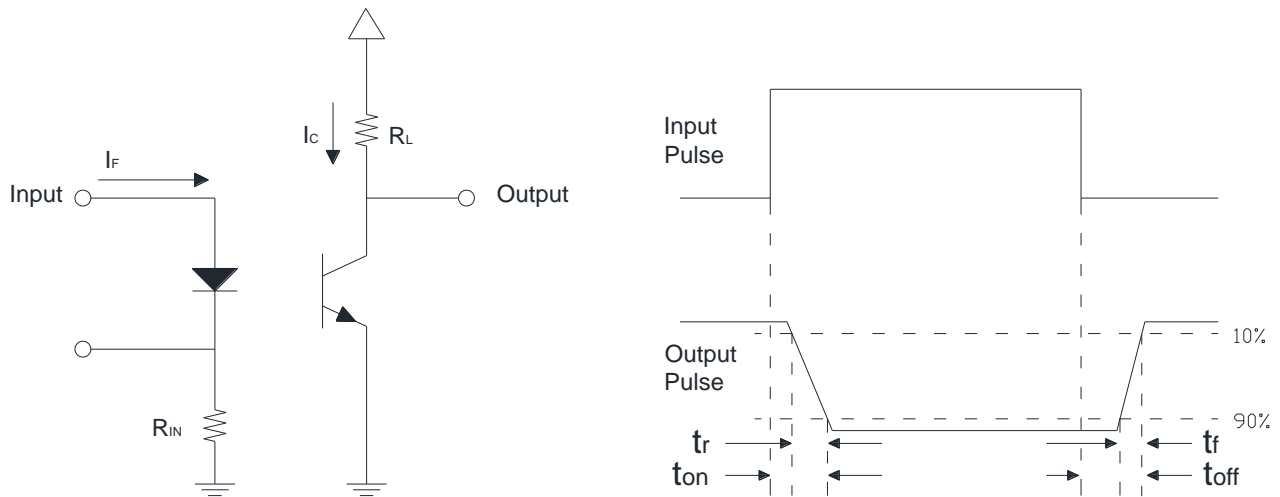
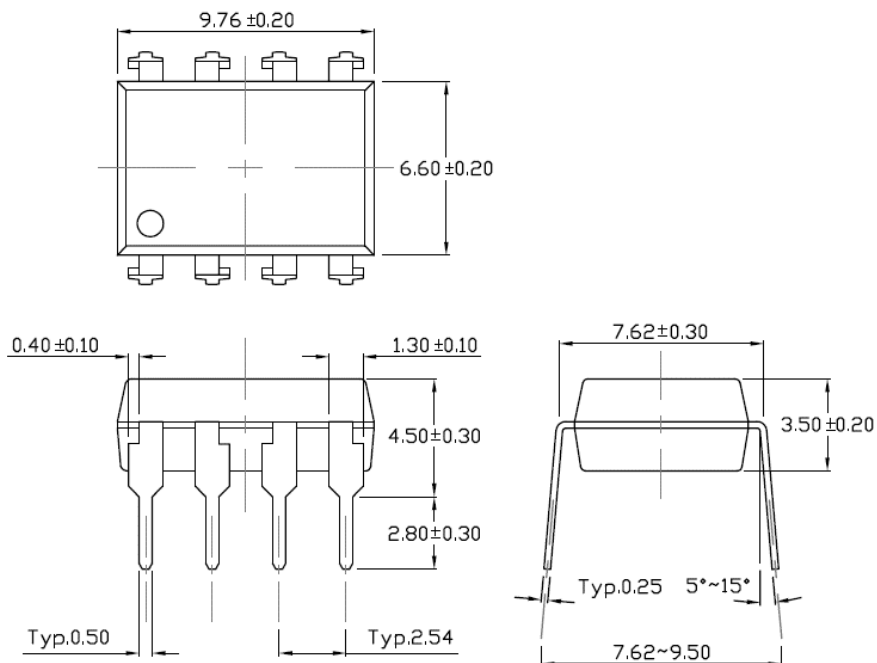


Figure 12: Switching Time Test Circuits

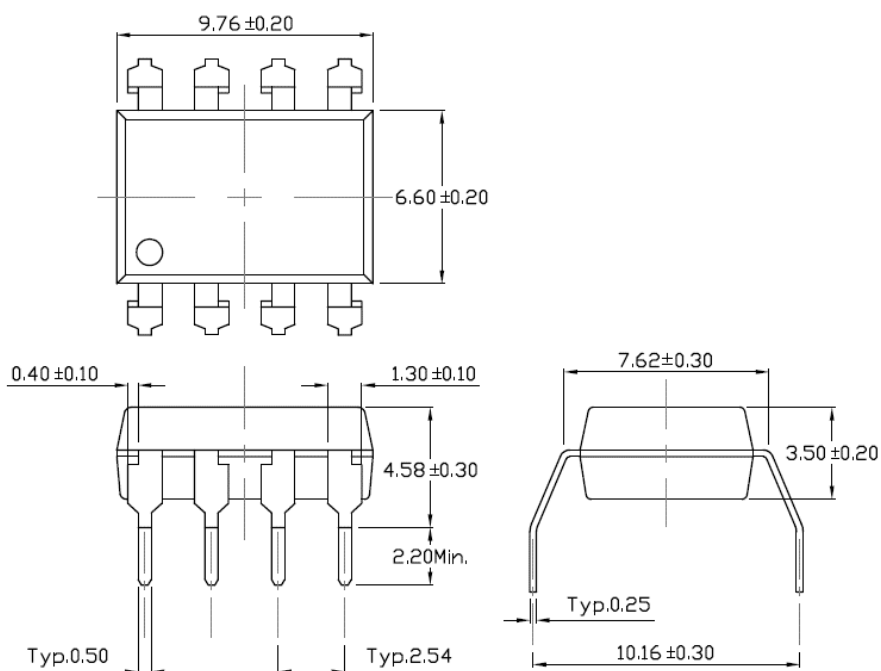


Package Dimension *Dimensions in mm unless otherwise stated*

Standard DIP – Through Hole

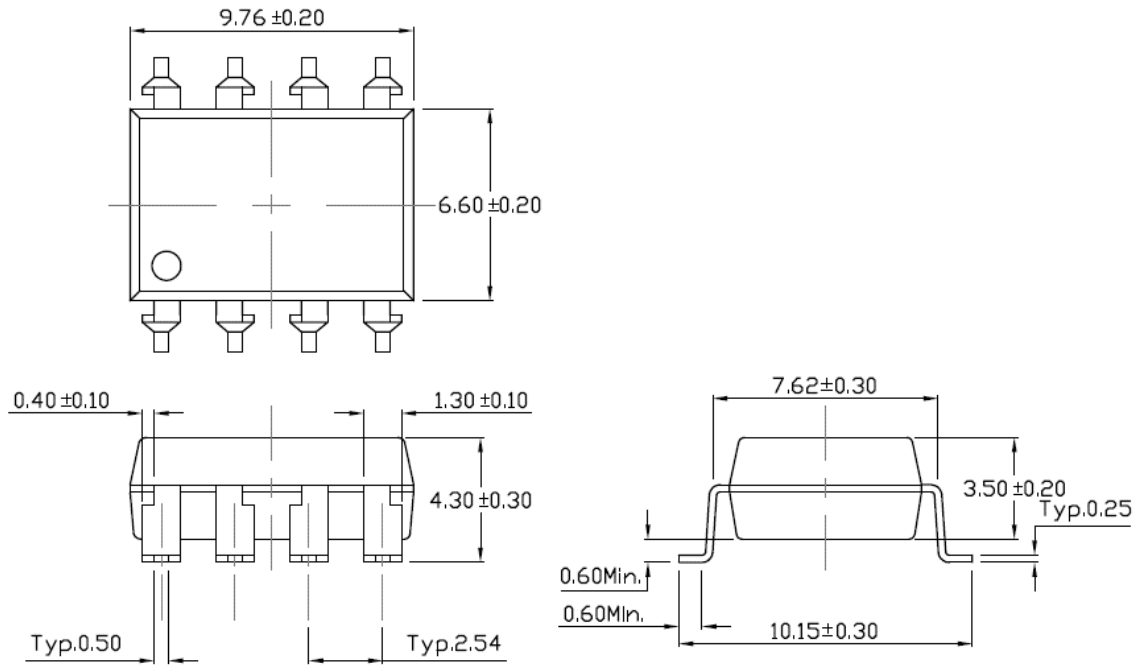


Gullwing (400mil) Lead Forming – Through Hole (M Type)

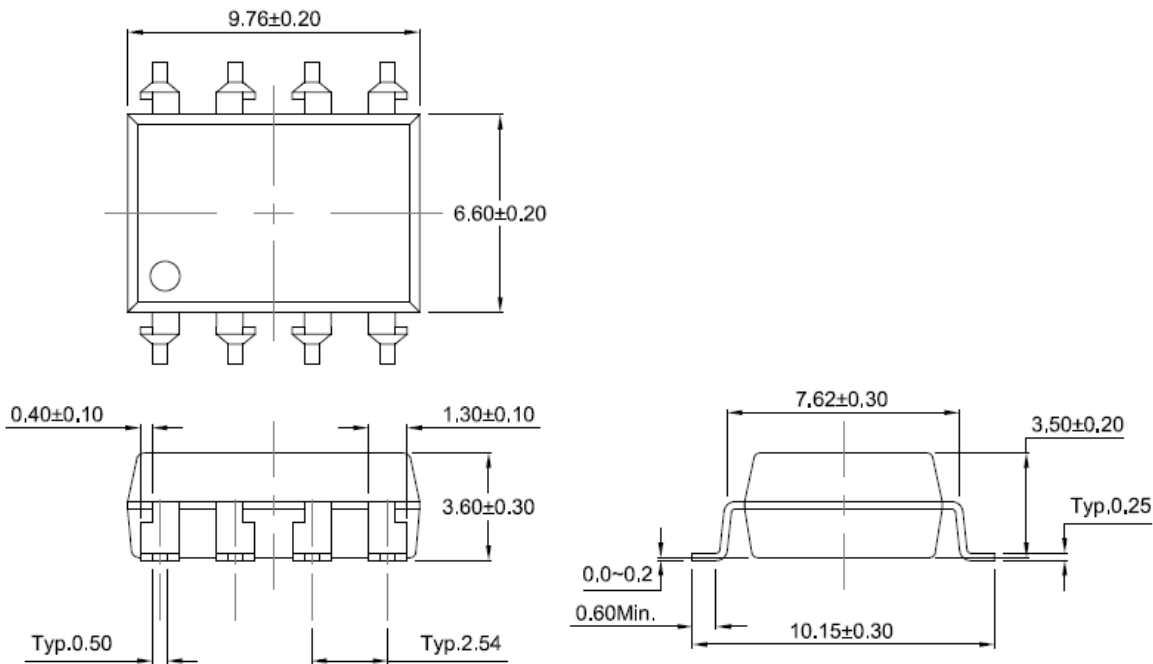




Surface Mount Lead Forming (S Type)



Surface Mount (Low Profile) Lead Forming (SL Type)

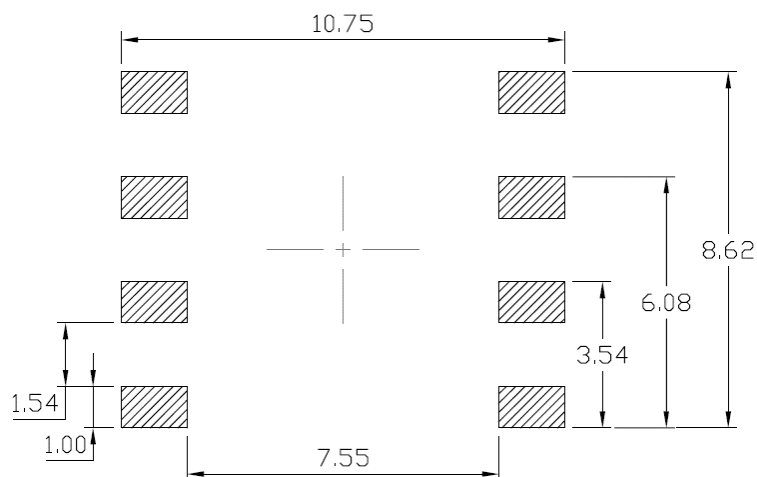




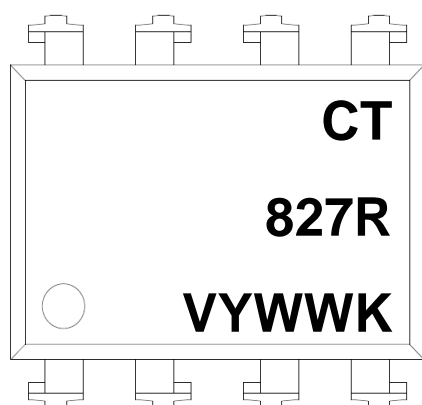
CT827 Series

DC Input 8-Pin Phototransistor Optocoupler

Recommended Solder Mask *Dimensions in mm unless otherwise stated*



Device Marking



Note:

- CT : Denotes "CT Micro"
- 827 : Product Number
- R : CTR Rank
- V : VDE Option
- Y : Fiscal Year
- WW : Work Week
- K : Production Code

**Ordering Information****CT827X(V)(Y)(Z)**

CT =Denotes "CT Micro"

827 =Product Number

X = Part No. (X=A, B or None)

V = VDE Option (V or None)

Y = Lead form option (S, SL, M or none)

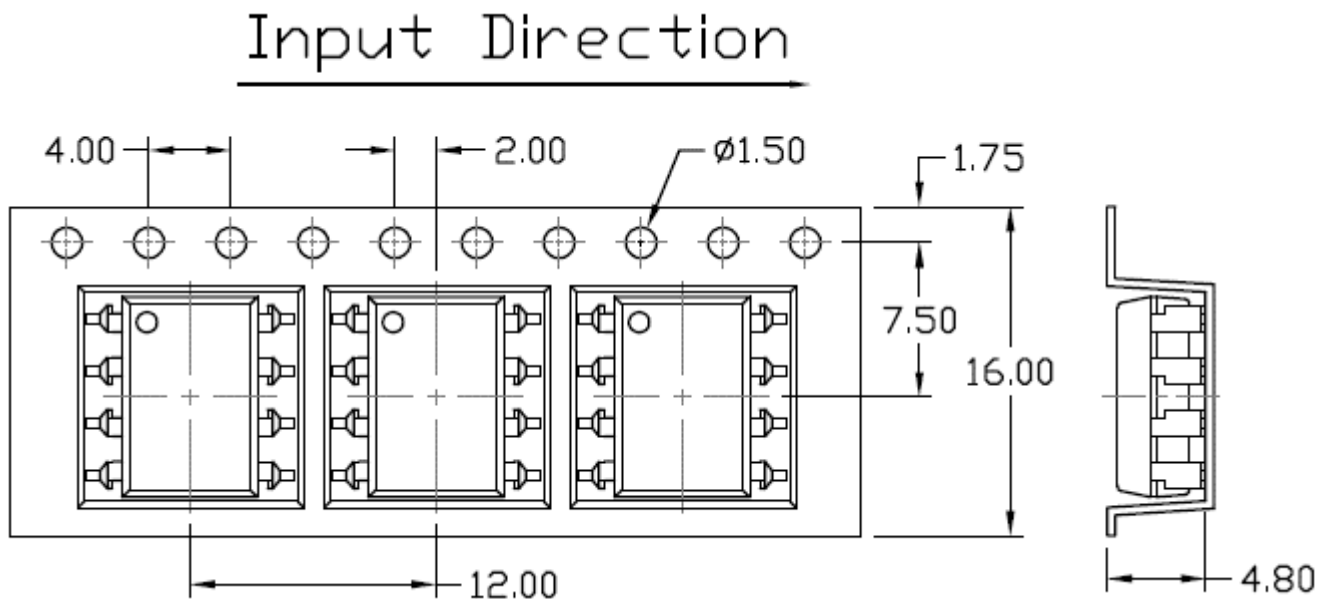
Z = Tape and reel option (T1, T2 or none)

Option	Description	Quantity
None	Standard 8 Pin Dip	40 Units/Tube
M	Gullwing (400mil) Lead Forming	40 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming– With Option 2 Taping	1000 Units/Reel

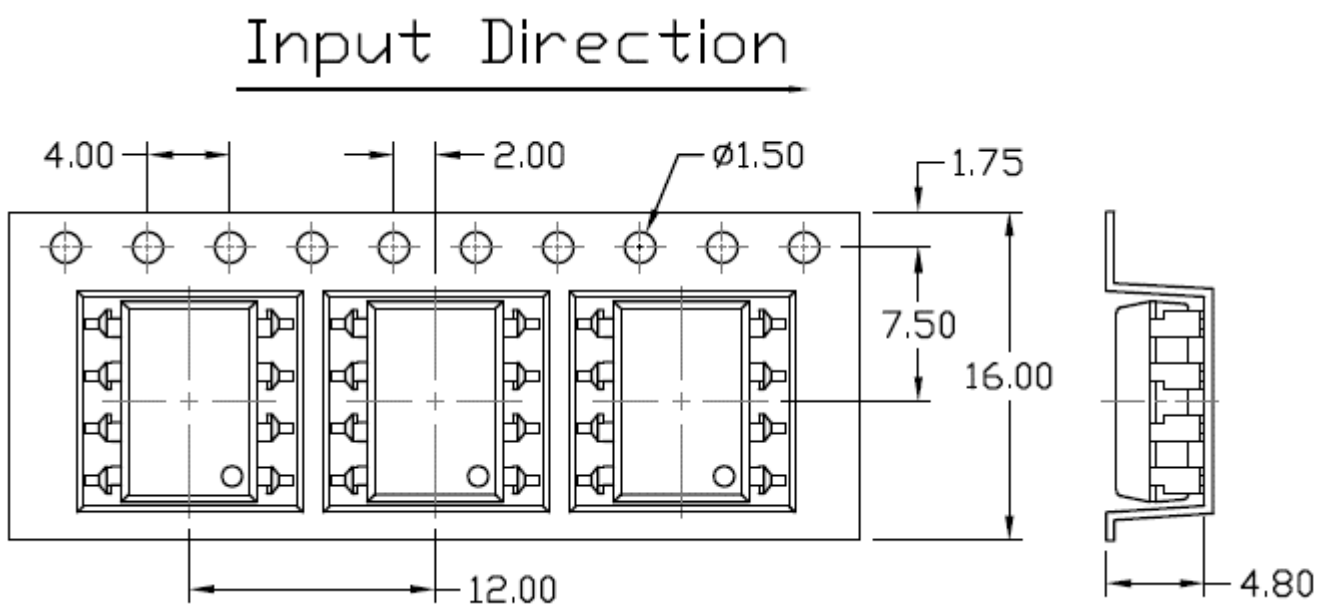


Carrier Tape Specifications *Dimensions in mm unless otherwise stated*

Option S(T1) & SL(T1)



Option S(T2) & SL(T2)





Wave soldering (follow the JEDEC standard JESD22-A111)

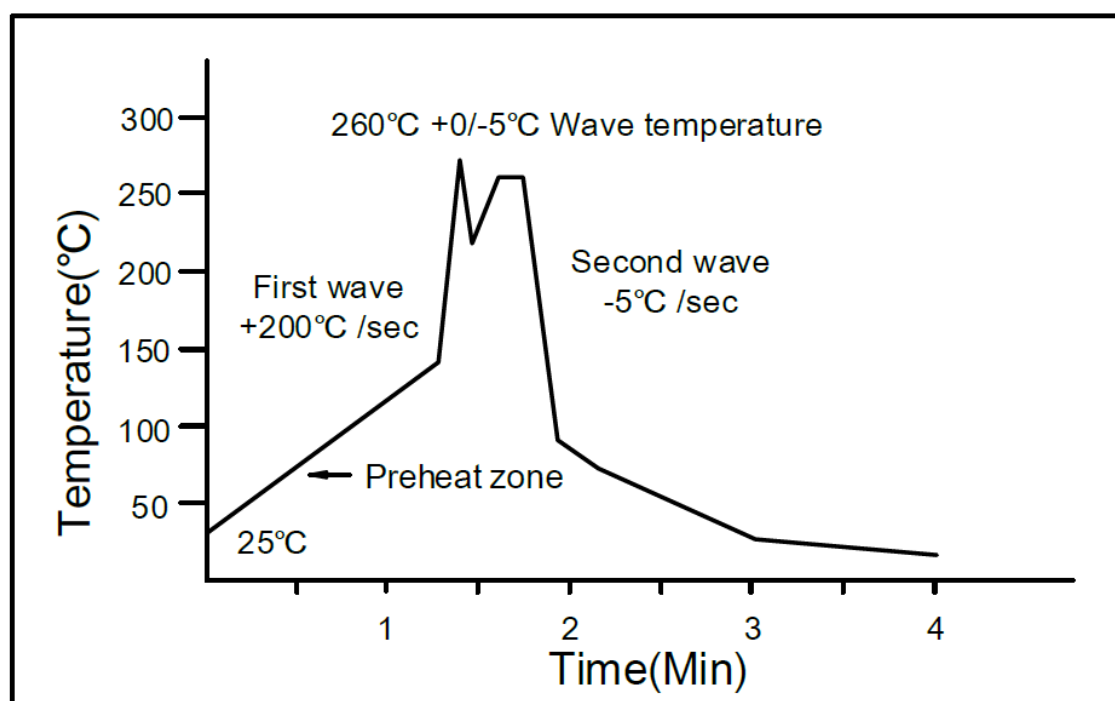
One time soldering is recommended within the condition of temperature.

Temperature: $260 \pm 0/-5^\circ\text{C}$.

Time: 10 sec.

Preheat temperature: 25 to 140°C .

Preheat time: 30 to 80 sec.



Hand soldering by soldering iron

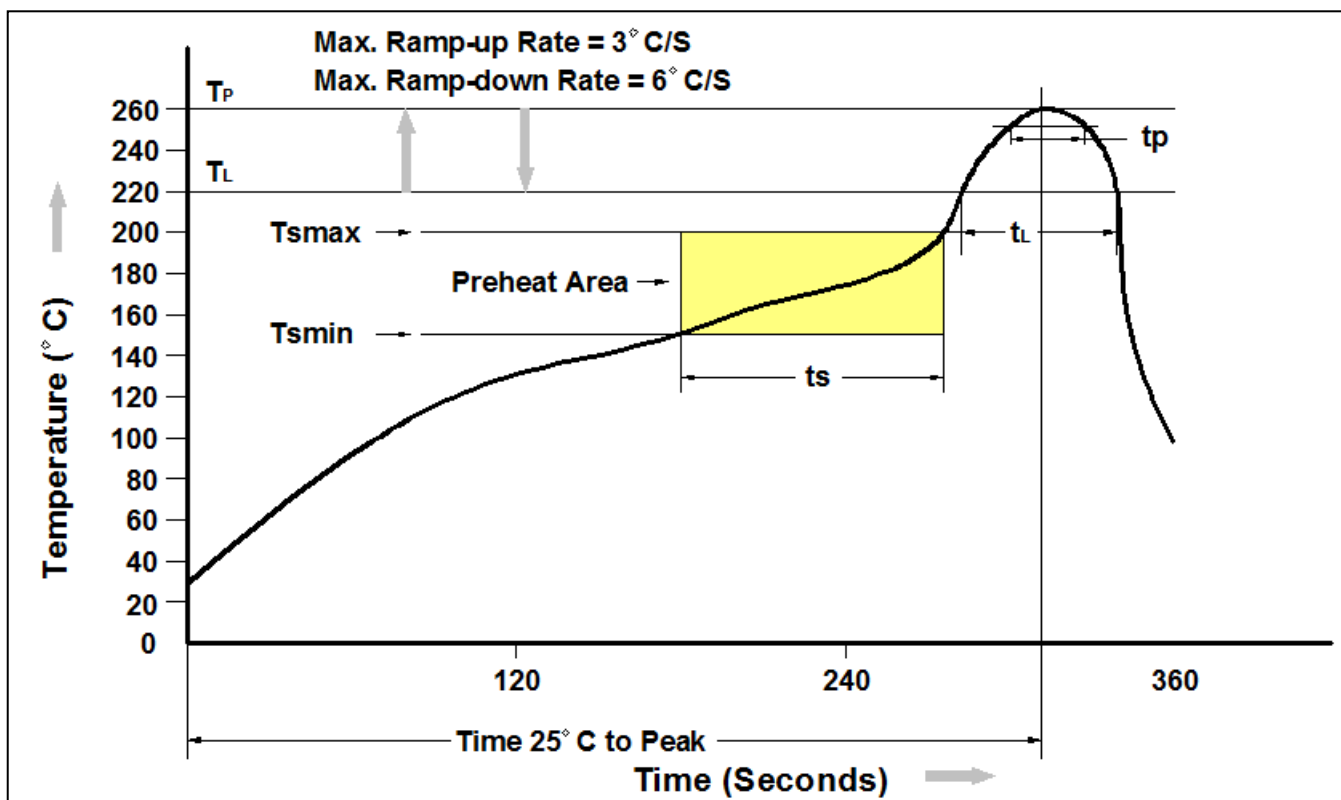
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: $380 \pm 0/-5^\circ\text{C}$

Time: 3 sec max.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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